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FAIRCHILD

SEMICONDUCTOR™

MM74HC151
8-Channel Digital Multiplexer

General Description

The MM74HC151 high speed Digital multiplexer utilizes advanced silicon-gate CMOS technology. Along with the high noise immunity and low power dissipation of standard CMOS integrated circuits, it possesses the ability to drive 10 LS-TTL loads. The MM74HC151 selects one of the 8 data sources, depending on the address presented on the A, B, and C inputs. It features both true (Y) and comple-ment (W) outputs. The STROBE input must be at a low logic level to enable this multiplexer. A high logic level at the STROBE forces the W output HIGH and the Y output LOW.

The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by inter-nal diode clamps to V_{CC} and ground.

Features

■ Typical propagation delay data select to output Y: 26 ns

■ Wide operating supply voltage range: 2–6V

■ Low input current: 1 μA maximum

■ Low quiescent supply current: 80 μA maximum (74HC)

■ High output drive current: 4 mA minimum

Ordering Code:

Order Number	Package Number	Package Description
MM74HC151M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC151SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC151MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC151N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram

Pin Assignments for DIP, SOIC, SOP and TSSOP

Top View
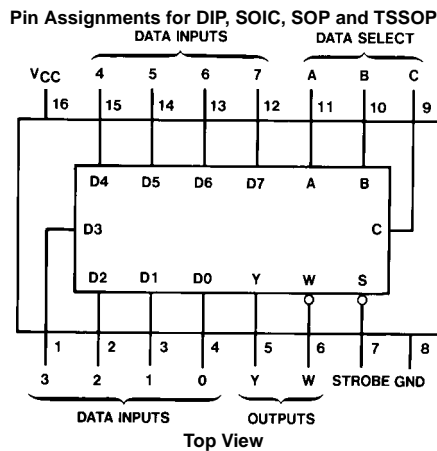
Truth Table

Inputs				Outputs	
Select			Strobe		
C	B	A	S	Y	W
X	X	X	H	L	H
L	L	L	L	D0	$\overline{D0}$
L	L	H	L	D1	$\overline{D1}$
L	H	L	L	D2	$\overline{D2}$
L	H	H	L	D3	$\overline{D3}$
H	L	L	L	D4	$\overline{D4}$
H	L	H	L	D5	$\overline{D5}$
H	H	L	L	D6	$\overline{D6}$
H	H	H	L	D7	$\overline{D7}$

H = HIGH Level, L = LOW Level, X = Don't Care
D0, D1...D7 = the level of the respective D input

Logic Diagram
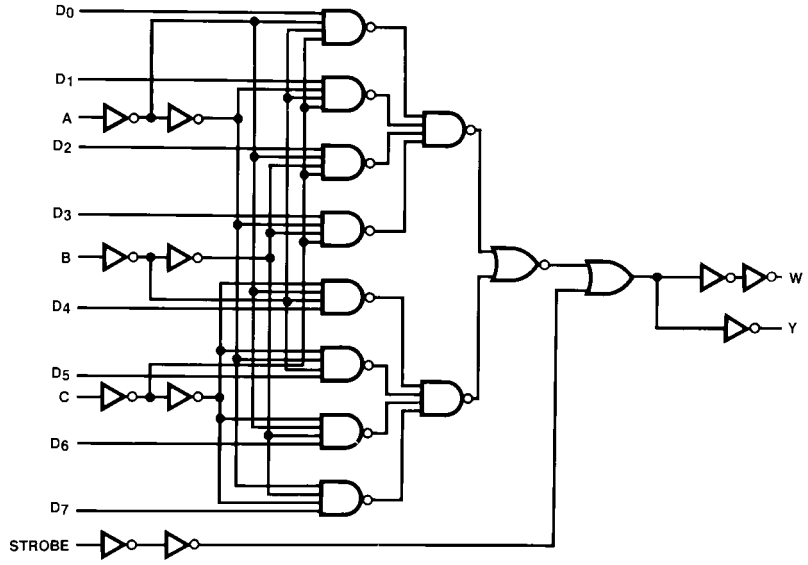
Absolute Maximum Ratings(Note 1)

(Note 2)

Supply Voltage (V_{CC})	−0.5 to +7.0V
DC Input Voltage (V_{IN})	−1.5 to V_{CC} +1.5V
DC Output Voltage (V_{OUT})	−0.5 to V_{CC} +0.5V
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA
DC Output Current, per pin (I_{OUT})	±25 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±50 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Power Dissipation (P_D)	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T_L)	260°C
(Soldering 10 seconds)	

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	2	6	V
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temperature Range (T_A)	−40	+85	°C
Input Rise or Fall Times			
(t_r, t_f) V_{CC} = 2.0V		1000	ns
V_{CC} = 4.5V		500	ns
V_{CC} = 6.0V		400	ns

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

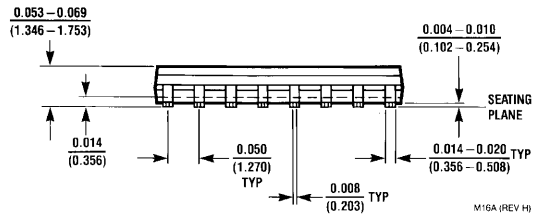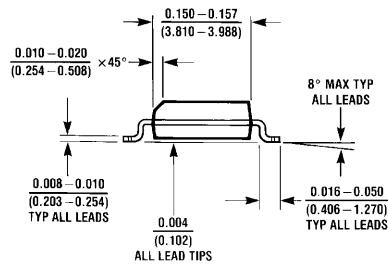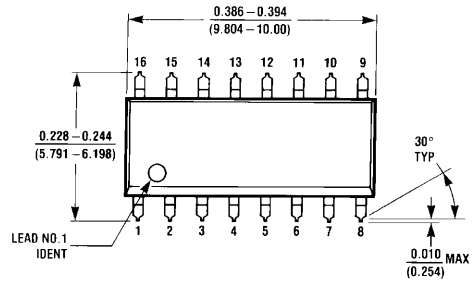**Note 3:** Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics (Note 4)

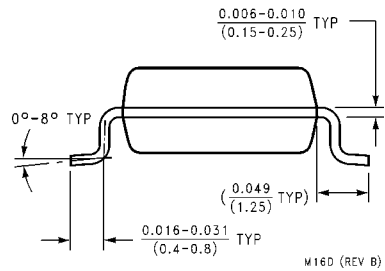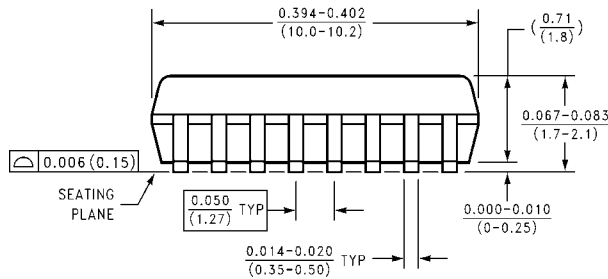| Symbol	Parameter	Conditions	V_{CC}	T_A = 25°C	T_A = −40 to 85°C	T_A = −55 to 125°C	Units
				Typ	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage		2.0V		1.5	1.5	1.5	V
			4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V_{IL}	Maximum LOW Level Input Voltage		2.0V		0.5	0.5	0.5	V
			4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V_{OH}	Minimum HIGH Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $|I_{OUT}| \leq 20$ µA	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		V_{IN} = V_{IH} or V_{IL} $|I_{OUT}| \leq 4.0$ mA	4.5V	4.2	3.98	3.84	3.7	V
		$|I_{OUT}| \leq 5.2$ mA	6.0V	5.7	5.48	5.34	5.2	V
V_{OL}	Maximum LOW Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $|I_{OUT}| \leq 20$ µA	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		V_{IN} = V_{IH} or V_{IL} $|I_{OUT}| \leq 4.0$ mA	4.5V	0.2	0.26	0.33	0.4	V
		$|I_{OUT}| \leq 5.2$ mA	6.0V	0.2	0.26	0.33	0.4	V
I_{IN}	Maximum Input Current	V_{IN} = V_{CC} or GND	6.0V		±0.1	±1.0	±1.0	µA
I_{CC}	Maximum Quiescent Supply Current	V_{IN} = V_{CC} or GND I_{OUT} = 0 µA	6.0V		8.0	80	160	µA

Note 4: For a power supply of 5V ±10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics

$V_{CC} = 5V$, $T_A = 25°C$, $C_L = 15$ pF, $t_r = t_f = 6$ ns

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
t_{PHL}, t_{PLH}	Maximum Propagation Delay A, B or C to Y		26	35	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay A, B or C to W		27	35	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay Any D to Y		22	29	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay any D to W		24	32	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay Strobe to Y		17	23	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay Strobe to W		16	21	ns

AC Electrical Characteristics

$C_L = 50$ pF, $t_r = t_f = 6$ ns (unless otherwise specified)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25°C$ Typ	$T_A = 25°C$ Guaranteed Limits	$T_A = -40$ to $85°C$ Guaranteed Limits	$T_A = -55$ to $125°C$ Guaranteed Limits	Units
t_{PHL}, t_{PLH}	Maximum Propagation Delay A, B or C to Y		2.0V	90	205	256	300	ns
			4.5V	31	41	51	60	ns
			6.0V	26	35	44	51	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay A, B or C to W		2.0V	95	205	256	300	ns
			4.5V	32	41	51	60	ns
			6.0V	27	35	44	51	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay any D to Y		2.0V	70	195	244	283	ns
			4.5V	27	39	49	57	ns
			6.0V	23	33	41	48	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay any D to W		2.0V	75	185	231	268	ns
			4.5V	29	37	46	54	ns
			6.0V	25	32	40	46	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay Strobe to Y		2.0V	50	140	175	203	ns
			4.5V	21	28	35	41	ns
			6.0V	18	24	30	35	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay Strobe to W		2.0V	45	127	159	185	ns
			4.5V	20	25	32	37	ns
			6.0V	17	22	28	32	ns
t_{TLH}, t_{THL}	Maximum Output Rise and Fall Time		2.0V	30	75	95	110	ns
			4.5V	8	15	19	22	ns
			6.0V	7	13	16	19	ns
C_{PD}	Power Dissipation Capacitance (Note 5)	(per package)		110				pF
C_{IN}	Maximum Input Capacitance			5	10	10	10	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

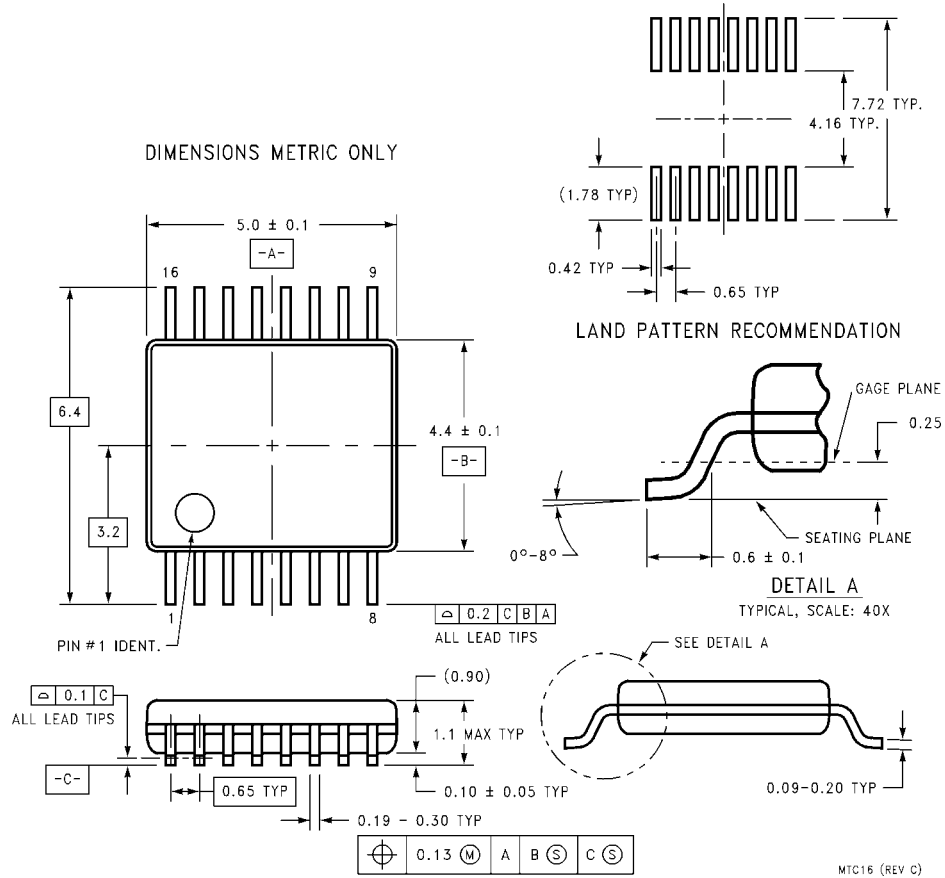**Physical Dimensions** inches (millimeters) unless otherwise noted

0.386 – 0.394
(9.804 – 10.00)

16 15 14 13 12 11 10 9

0.228 – 0.244
(5.791 – 6.198)

30°
TYP

LEAD NO.1
IDENT

1 2 3 4 5 6 7 8

0.010 MAX
(0.254)

0.150 – 0.157
(3.810 – 3.988)

0.010 – 0.020
(0.254 – 0.508) × 45°

8° MAX TYP
ALL LEADS

0.053 – 0.069
(1.346 – 1.753)

0.004 – 0.010
(0.102 – 0.254)

SEATING
PLANE

0.008 – 0.010
(0.203 – 0.254)
TYP ALL LEADS

0.004
(0.102)
ALL LEAD TIPS

0.016 – 0.050
(0.406 – 1.270)
TYP ALL LEADS

0.014
(0.356)

0.050
(1.270)
TYP

0.008
(0.203)
TYP

0.014 – 0.020
(0.356 – 0.508)
TYP

M16A (REV H)

16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M16A

16   9

0.295 – 0.319
(7.5 – 8.1)

0.205 – 0.213
(5.2 – 5.4)

1   8

0.394 – 0.402
(10.0 – 10.2)

(0.71)
(1.8)

0.006 – 0.010
(0.15 – 0.25) TYP

0.067 – 0.083
(1.7 – 2.1)

0° – 8° TYP

0.006 (0.15)

SEATING
PLANE

0.050
(1.27) TYP

0.000 – 0.010
(0 – 0.25)

(0.049
(1.25) TYP)

0.014 – 0.020
(0.35 – 0.50) TYP

0.016 – 0.031
(0.4 – 0.8) TYP

M16D (REV B)
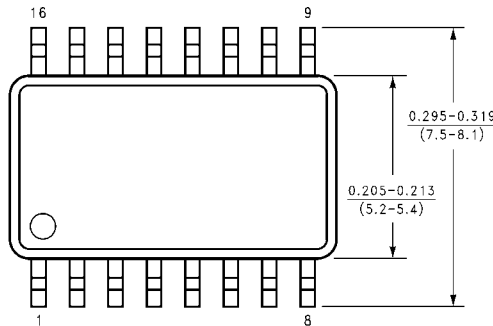
16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M16D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

DIMENSIONS METRIC ONLY

5.0 ± 0.1

-A-

16   9

6.4

4.4 ± 0.1

-B-

3.2

1   8

⌂ 0.2 C B A
ALL LEAD TIPS

PIN #1 IDENT.

⌂ 0.1 C
ALL LEAD TIPS

-C-

0.65 TYP

0.19 – 0.30 TYP

(0.90)

1.1 MAX TYP

0.10 ± 0.05 TYP

⊕ 0.13 Ⓜ A B Ⓢ C Ⓢ

7.72 TYP.

4.16 TYP.

(1.78 TYP)

0.42 TYP

0.65 TYP

LAND PATTERN RECOMMENDATION

GAGE PLANE

0.25

0°–8°

0.6 ± 0.1

SEATING PLANE

DETAIL A
TYPICAL, SCALE: 40X

SEE DETAIL A

0.09–0.20 TYP

MTC16 (REV C)

16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC16

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)
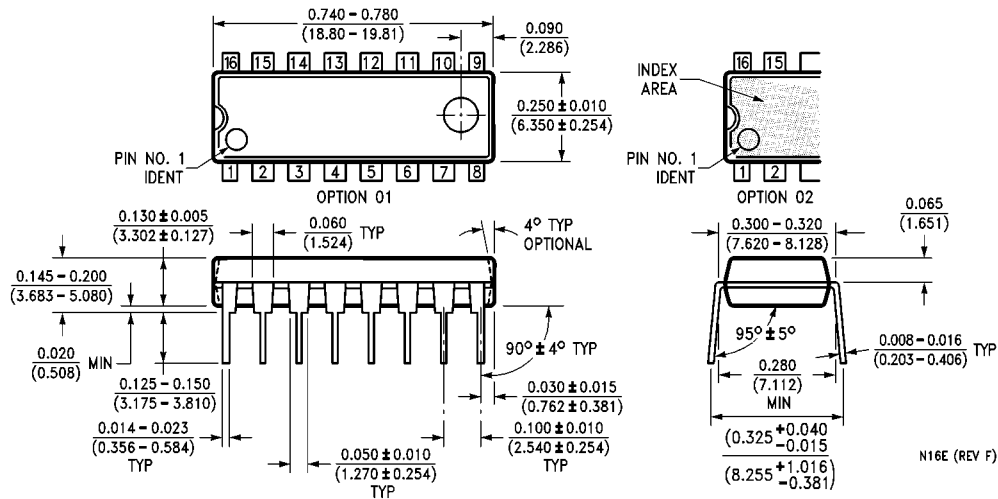
16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N16E

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